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(54) STACKED MODULE ARRANGEMENT

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(57) **ABSTRACT**

A stacked module arrangement includes: a first molded electronic module; a second molded electronic module; and an interface by which the first molded electronic module and the second molded electronic module are physically and electrically connected to one another in a stacked configuration. The first molded electronic module is a power electronic module having a maximum breakdown voltage of at least 40 V and a maximum DC current of at least 10 A.